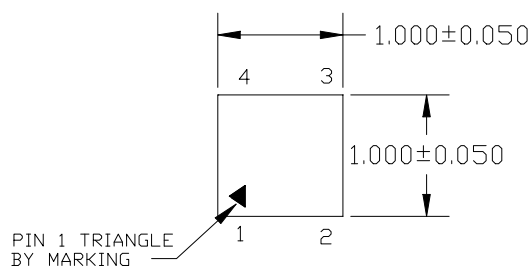


TITLE

4 LEAD TDFN 1.0x1.0mm PACKAGE OUTLINE & RECOMMENDED LAND PATTERN

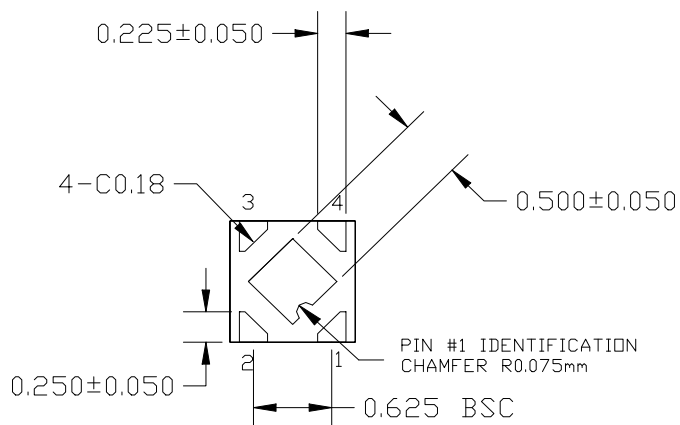
DRAWING # TDFN1010-4LD-PL-1

UNIT MM



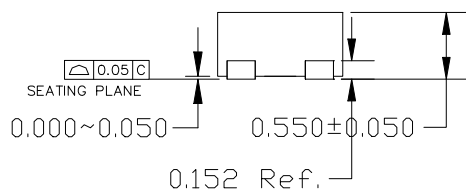
TOP VIEW

NOTE: 1, 2, 3



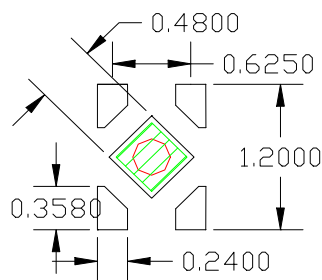
BOTTOM VIEW

NOTE: 1, 2, 3



SIDE VIEW

NOTE: 1, 2, 3



RECOMMENDED LAND PATTERN

NOTE: 4, 5

NOTE:

1. MAX PACKAGE WARPAGE IS 0.05 MM
2. MAX ALLOWABLE BURR IS 0.076MM IN ALL DIRECTIONS
3. PIN #1 IS ON TOP WILL BE LASER MARKED
4. RED CIRCLE IN LAND PATTERN INDICATE THERMAL VIA. SIZE SHOULD BE 0.30-0.3 MM IN DIAMETER AND SHOULD BE CONNECTED TO GND FOR MAX THERMAL PERFORMANCE
5. GREEN RECTANGLES (SHADED AREA) INDICATE SOLDER STENCIL OPENING ON EXPOSED PAD AREA. SIZE SHOULD BE 0.40x0.40 MM.

Rev	ECN	Originator	Change	Reason
A	012312HC10	S. YEH	New release	Per George C.